



One-stop service makes production easier

PCB Manufacturing Capacity

Item	Specification
Material	FR-4, FR1, FR2, CEM-1, CEM-3; Rogers, Teflon, Arlon; Aluminum Base, Copper Base, Ceramic, etc.
Remarks	High Tg CCL is Available (Tg>=180℃)
Finish Board Thickness	0.2 mm~6.00mm(8mil~126mil)
Surface Finish	Gold finger(>=0.13um), Immersion Gold(0.025~0.075um), Plating Gold(0.025~3.0um), HASL(5~20um), OSP(0.2~0.5um)
Shape	Routing, Punch, V-cut, Chamfer
Surface Treatment	Solder Mask(black, green, white, red, blue, thickness>=12um, Block, BGA)
	Silkscreen(black, yellow, white)
	Peel able mask(red, blue, thickness>=300um)
Minimum Core	0.075mm(3mil)
Copper Thickness	1/2 oz min; 12oz max
Min Trace Width & Line Spacing	0.075mm/0.075mm(3mil/3mil)
Min Hole Diameter for CNC Drilling	0.1mm(4mil)
Min Hole Diameter for Punching	0.6mm(35mil)
Biggest panel size	2000mm* 700mm
Hole Position	±0.075mm(3mil) CNC Drilling
Conductor Width(W)	±0.05mm(2mil) or ±20% of original
Hole Diameter(H)	PTH: ±0.075mm(3mil)
	Non PTH: ±0.05mm(2mil)
Outline Tolerance	±0.1mm(4mil) CNC Routing
Warp & Twist	0.70%
Insulation Resistance	10Kohm~20Mohm
Conductivity	<50ohm
Test Voltage	10~300V
Panel Size	110 x 100mm(min)
	2000 x 700mm(max)
Layer-layer misregistration	4 layers: 0.15mm(6mil)max
	6 layers: 0.25mm(10mil)max
Min spacing between hole edge to circuitry pattern of an inner layer	0.25mm(10mil)
Min spacing between board outline to circuitry pattern of an inner layer	0.25mm(10mil)
Board thickness tolerance	4 layers: ±0.13mm(5mil)